LA SG08CP2

Premium Edition Standard Green 8 mil

Light Avenue Premium Edition LED series is designed for high performance consumer applications. As this die can be driven at very high currents compared to the chip size, an outstanding cost vs. performance ratio can be obtained. Furthermore this volume emitting chip can withstand ESD voltage up to 1kV.

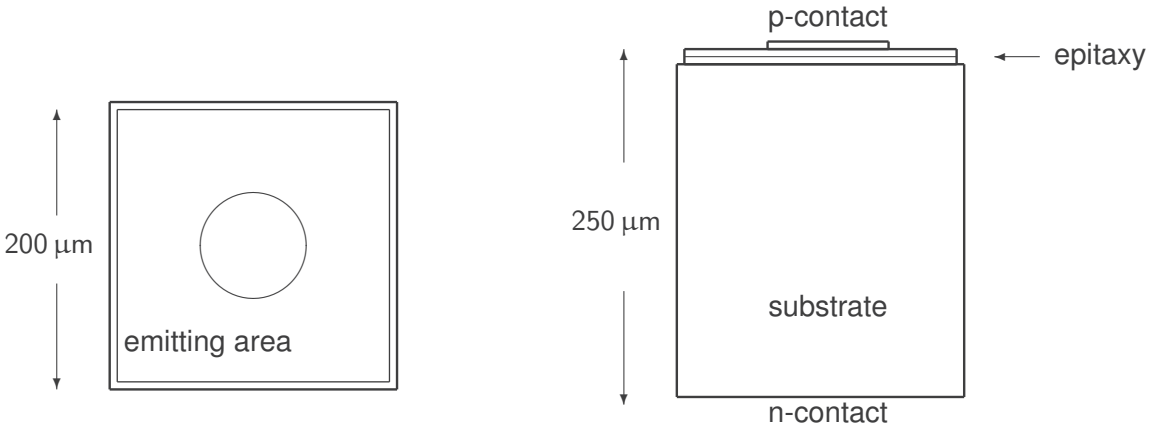
Features

- High brightness InGaN chip
- Volume emitting device
- Substrate SiC
- Grouping: radiant power, wavelength
- ESD withstand voltage up to 1kV

Applications

- Solid state lighting
- Lamps
- Displays
- Light indicators

Delineation



Mechanical characteristics

DESCRIPTION		MINIMUM	TYPICAL[1]	MAXIMUM
Chip size	(µm)	175	200	225
Chip height	(µm)	230	250	270
Bond pad diameter	(µm)	100	120	140
Top contact		Anode (p), gold		
Bottom contact		Cathode (n), gold alloy		
Die attach		Epoxy bonding		

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Electro-optical characteristics ($T_A = 25°C$)[2]

PARAMETER	SYMBOL	CONDITION	MIN.	TYP.[1]	MAX.	UNIT
Forward voltage	V_F	$I_F = 20\,mA$	2.70		3.90	V
Reverse voltage	V_R	$I_R = 10\,\mu A$	5			V
Dominant wavelength	λ_{dom}	$I_F = 20\,mA$	515		537.5	nm
Radiant power	Φ_e	$I_F = 20\,mA$	1.0	1.6		mW

Maximum ratings ($T_A = 25°C$)[3]

PARAMETER	SYMBOL	VALUE	UNIT
Operating temperature range	T_{op}	-40...85	°C
Forward current	I_F	30	mA
Pulse current	I_P	100	mA
Junction temperature	T_j	135	°C

Binning ($I_F = 20\,mA$)

		WAVELENGTH (NM)							
		515-520	517.5-522.5	520-525	522.5-527.5	525-530	527.5-532.5	530-535	532.5-537.5
Radiant power (mW)	> 1	W7	WM7	X7	XM7	Y7	YM7	Z7	ZM7
	> 1.25	W8	WM8	X8	XM8	Y8	YM8	Z8	ZM8
	> 1.6	W9	WM9	X9	XM9	Y9	YM9	Z9	ZM9
	> 2	W10	WM10	X10	XM10	Y10	YM10	Z10	ZM10
	> 2.5	W11	WM11	X11	XM11	Y11	YM11	Z11	ZM11
	> 3.2	W12	WM12	X12	XM12	Y12	YM12	Z12	ZM12

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Handling and Storage Conditions

Storage time for wafers in sealed condition is not limited by the die itself, but may be limited by the adhesion of the blue foil (storage ambient conditions: $T_a = 15 \ldots 30°C$; relative humidity: < 60%, vertical storage). Therefore we ship the dice without any limitation of shelf life. Customer has to make sure that there is no glue from the adhesive foil on the backside either by a die shear test or by visual inspection of the backside before production. The hermetically sealed shipment lot shall be opened under temperature and moisture controlled cleanroom environment only. Customers have to follow the according rules for desposition as the material can be hazardous for humans and the environment. Dice have to be handled ESD sensitive.

Packing

Chips are placed on a blue foil inside a 6 inch ring or alternatively on a blue foil (mylar) only. For shipment the wafers of a shipment lot are arranged to stacks. Please use the recycling operators familiar to you. If required you can ask for our help. Please get in touch with your nearest sales office. By agreement we will take packing material back, if sorted. Transport costs of any kind must be paid by customers. For packing material that is returned to us unsorted or which we are not obliged to accept, any costs incurred will be invoiced to you.

Design Objectives

The chip design was developed and released based on the producer's standard assembly procedures and packaging. Bond strength properties are in accordance to MIL-STD-750D, method 2037. Whether the chip fits to the customer's products with its according die and wire bond procedures and packaging must be evaluated by the customer himself. If workability problems arise after this release a mutually conducted problem solving procedure has to be set up, if the chips are suspected of contributing to the problems.The chips are produced with best effort, but on chip level a subset of the chip characteristics can be determined only. Performance of the chip in the customer's products can only be determined by the customer himself.

Returns and Complaints

For complaints and returns of material a RMA-number is necessary. Samples for analysis purposes can be send to us without credit.

Shipping Conditions

If not otherwise arranged, the "General Terms of Business of Chips 4 Light GmbH" apply for any shipment. If this document is not familiar to you, please request it at our nearest sales office.

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- The information describes the type of component and shall not be considered as assured characteristics. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.
- Lead free product - RoHS compliant.
- The quality level of the final visual inspection shall comply to an AQL of 1.0 (according to MIL-STD-105E, level II), if the customer performes an incoming visual inspection of a shipment.

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- All chips are checked according to the producer's specification of the visual inspection. If this document is not familiar to you, please request it at our nearest sales office.

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[1]Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

[2]Measurements are done with an accuracy of $\pm$15%. Correlation to customer's equipment and products is required.

[3]Maximum ratings are package dependent and may differ between packages. The forward current is not limited by the die but by the effect of the LED junction temperature on the package. If you need more information on pulsed operation, please contact your next sales office about possible driving conditions. If not otherwise specified the maximum pulse current may not exceed the maximum current in continuous mode.

[4]A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

[5]Life support devices or systems are intended(a) to be implanted in the human body,or(b) to support and/or maintain and sustain human life.If they fail, it is reasonable to assume that the health and the life of the user may be endangered..

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